Start of the Final H2020 Round: Calls of Relevance for Smart Systems (Integration)

Wolfgang Gessner, EPoSS e.V.

16.01.2019

ECS BROKERAGE EVENT 2019

15 & 16 January Hotel Le Plaza, Brussels EPOSS European Technology Hatforr on Smart Systems Integration

E Po S S

SMART SYSTEMS...

are sensor-actuator based systems ...

С

- are able to describe a situation and diagnose it
- are predictive, able to decide or help to decide
- mutually address and identify each other
- enable the product to interact with the environment.

They are as small as possible, networked & energy autonomous



EXAMPLES

... from the major application domains



MEDICAL



Intraocular pressure measurement device (Sensimed, STM)

INDUSTRIAL



Recognition system for dangerous substances (FhG IPM)

AUTOMOTIVE



Advanced driver assistance systems (Bosch)



Smart systems for robots in collaborative environments (Bosch)





Integrated design and manufacturing Integration at systems level: realisation of miniaturised systems

Integration into the macro-system

Integration into the application environment



--- EPoSS

- 2005 First steps
- 2006 Vision paper and first SRA
- 06.07.2006 EPoSS Launch, Brussels
- 18.09.2013 Transformation into an Association with legal status

OBJECTIVES

- Give a voice to the European Microsystems and Smart Systems Community
- Promote Smart Systems R&D
- Contribute to European R&D&I Policy
- Realise advantages for the members





EPOSS IN THE EUROPEAN CONTEXT







Interactions and alliances, incl. common roadmaps, MoUs, aligned strategies events, with other initiatives and networks

.....



FUNDING LANDSCAPE FOR SMART SYSTEMS INTEGRATION PROJECTS



H2020 2014-2020: 80 B€ BUDGET

Excellent Science

- Frontier Research (ERC)
- Future and Emerging Technologies (FET) ICT (SSI
- Skills and career development (Marie Skłodowska-Curie)
- Research Infrastructure

Societal Challenges

- SSI ICT Health, demographic change and wellbeing
- Food security, sustainable agriculture, **SSI** ICT water, and the bio-based economy (SSI) ICT)
- Secure, clean and efficient energy
- Smart, green and integrated transport SSI ICT
- Climate action, environment, resource efficiency, and raw materials (SSI ICT)
- Inclusive, innovative and reflective societies **ICT**
- Secure societies (SSI) ICT





Space Access to risk finance Innovation in SMEs ICT SSI

Manuf. & Processing,

ICT ICT SSI

Biotechnology

Industrial Leadership

Leadership in enabling and industrial technologies

Nanotech., Advanced Materials, ICT SSI

PUBLIC PRIVATE PARTNERSHIPS > 23 B€ OF INVESTMENT







ECSEL Joint Undertaking

Electronic Components and Systems for European Leadership



"To keep Europe at the forefront of electronic components and systems"

[10/07/2013 COM(2013) 494 final] EPoSS, AENEAS and ARTEMIS-IA are private partners in the ECSEL JTI: Electronic Components and Systems for European Leadership Joint Technology Initiative



© EPoSS 2019 ECS BROKERAGE EVENT 2019, BRUSSELS



ECSEL Joint Undertaking

Electronic Components and Systems for European Leadership



Call 2019 launch: 06 February 2019 PO: 07 May 2019 FPP: 18 September 2019

More than

ECSEL So Far

Calls

1600 Projects

participations

2.6 bn€ 1.2 bn€ 1.4 bn€ RDI cost

EU and National

industries own financing

© EPoSS 2019 ECS BROKERAGE EVENT 2019, BRUSSELS

OTHER OPPORTUNITIES



Eureka (EURIPIDES², PENTA, ITEA3, ...)

SAE (SmartAnythingEverywhere), I4MS (ICT Innovation for Manufacturing SMEs)

JPI MYBL (Joint Programming Initiative More Years Better Lives)

DIH (Digital Innovation Hubs)

EIT (Digital, Health, Food, Climate-KIC, Raw Materials, InnoEnergy)

•••

© EPoSS 2019 ECS BROKERAGE EVENT 2019, BRUSSELS

Call – Information and Communication Technologies (H2020-ICT-2018-2020)



 ICT-03-2018-2019: Photonics Manufacturing Pilot Lines for Photonic Components and Devices
 Deadline: 28 March 2019, IA: 30 M€

Deadline: 28 March 2019, IA: 30 M€

- ICT-05-2019: Application driven Photonics components
 Deadline: 28 March 2019, IA: 30 M€, RIA: 45 M€, CSA: 1,5 M€
- ICT-06-2019: Unconventional Nanoelectronics
 Deadline: 29 March 2010, DIA: 20 MG
 - Deadline: 28 March 2019, RIA: 30 M€
- ICT-09-2019-2020: Robotics in Application Areas

Deadline: 28 March 2019, IA: 28 M€, RIA: 20 M€, CSA: 2 M€

ICT-06-2019: Unconventional Nanoelectronics



- - Europe at the forefront of advanced nanoelectronics \rightarrow Strategic design and manufacturing in Europe (avoiding critical dependencies)
 - Develop innovative solutions to industrial and societal challenges

Scope

Challenge

- Beyond-CMOS devices, e.g. guantum, spintronic, single electron devices
- Energy efficient architectures, e.g. neuromorphic and other hardware implementation
- Specific technological developments, e.g.
 - 3-D stacks (sequential / monolithic) \rightarrow compactness, heat dissipation...
 - Cryogenic electronics for advance computing (supercomputing, quantum computing...
- Design for advanced nanoelectronics

Instrume	nt	 RIA, TRL 4, 30 M€ (2-4 M€ per project), Deadline 28 March 2019 			
	©Ε	PoSS	2019	ECS BROKERAGE EVENT 2019, BRUSSELS	1 5



Call – Industrial Sustainability (H2020-NMBP-ST-IND-2018-2020)



LC-NMBP-32-2019: Smart materials, systems and structures for energy harvesting

Deadline (two-stage): 22 January 2019 / 03 September 2019, RIA: 41.1 M€



Main focus on materials, but explicitly mentioning

- Integrate sensor technologies (e.g. MEMS based sensor concepts) and the potential linkage with the Internet of Things (IoT)
- ... enable the development of wireless sensor networks, or, deployment of energy harvesting powered sensor nodes ...

Call – Sustainable food security (H2020-SFS-2018-2020)



SFS-37-2019: Integrated approaches to food safety controls across the food chain
 Deadline (two-stage): 23 January 2019 / 04 September 2019,

RIA: 8 M€



Should address:...efficient food safety control systems, supported by reliable authentication and traceability approaches, being implemented across the entire food chain, focusing on the combination of hazard monitoring and control options in the specific stages of the food chain

Call – Digital transformation in health and care (H2020-SC1-DTH-2018-2020)



 <u>SC1-DTH-01-2019: Big data and Artificial Intelligence for monitoring health status</u> and quality of life after the cancer treatment
 Deadline: 24 April 2010, PIA: 35 ME

Deadline: 24 April 2019, RIA: 35 M€

SC1-DTH-11-2019: Large scale pilots of personalised & outcome based integrated care

Deadline: 24 April 2019, IA: 20 M€

SC1-DTH-12-2020: Smart hospital of the future – coming soon

Call – Digitising and transforming European industry and services: automated road transport (H2020-DT-ART-2018-2019-2020)



- DT-ART-03-2019: Human centred design for the new driver role in highly automated vehicles
 Deadline: 25 April 2019, RIA: 8 M€
- DT-ART-04-2019: Developing and testing shared, connected and cooperative automated vehicle fleets in urban areas for the mobility of all
 Deadline: 25 April 2010, IA: 20 ME

Deadline: 25 April 2019, IA: 30 M€

Ο

© EPoSS 201	I9 ECS BROKERAGE EVENT 2019, BRUSSELS	1 9
-------------	---------------------------------------	-----

Call – Building a low-carbon, climate-resilient future: green vehicles (H2020-LC-GV-2018-2019-2020)



- LC-GV-03-2019: User centric charging infrastructure
 Deadline: 25 April 2019, IA: 35 M€
- LC-GV-04-2019: Low-emissions propulsion for long-distance trucks and coaches

Deadline: 25 April 2019, IA: 25 M€

Ο

 LC-GV-05-2019: InCo flagship on "Urban mobility and sustainable electrification in large urban areas in developing and emerging economies"
 Deadline: 25 April 2019, IA: 18 M€

© EPoSS 2019 ECS BROKERAGE EVENT 2019, BRUSSELS

Call – Digitising and transforming European industry and services: digital innovation hubs and platforms (H2020-DT-2018-2020)



DT-ICT-01-2019: Smart Anything Everywhere

Deadline: 02 April 2019, IA: 48 M€ (8 M€ per project), CSA: 1M€

- Area 1: Cyber-physical and embedded systems
- Area 2: Low energy computing, powering CPS and IoT
- Area 3: Flexible an Wearable Electronics
- Area 4: Digital Innovation hubs in underrepresented regions



Ο

 DT-NMBP-18-2019: Materials, manufacturing processes and devices for organic and large area electronics

Deadline (two-stage): 22 January 2019 / 03 September 2019, IA: 20 M€

© EPoSS 2019	ECS BROKERAGE EVENT 2019, BRUSSELS	2 1	l
--------------	------------------------------------	-----	---

DT-ICT-01-2019: Smart Anything Everywhere



o Challeng	•	Accelerate design, development and uptake of digital technologies by Europ industry - especially SMEs and mid-caps - in products that include innovative electronic components, software and systems, and especially in sectors who digital technologies are underexploited	ve
Scope	Of •	Area 3: Flexible and Wearable Electronics Help businesses in further maturing, innovating and validating their products with organic and large area electronics technologies, including wearable, portable and embedded objects Focus:	•
Instrumen	t •	 Access to design, technology and prototyping which are ready to use Application experiments driven by concrete user requirements and business IA, up to 8 M€ (part of 48 M€ for 4 areas), Deadline: 2 April 2019 	cases
	© EPoSS		2 2

DT-NMBP-18-2019: Materials, manufacturing processes and devices for organic and large area electronics



- Advance the technology readiness level of Organic / Large area Electronics
 → to advance its manufacturability
 - \rightarrow via demonstration of OLAE-enabled prototypes in selected applications

Scope	Proces integra	Materials: Electrical performance, processability, stability, lifetime in operation Processes: Seamless integration into traditional/new products, high speed integration processes on flexible substrates Prototyping of advanced products	
Instrument		RL 3-5, 20 M€ (4-5 M€ per project), co-funded by ICT and NMBP ammes, Deadline (2-step): 22 January 2019 and 5 September 2019	
	© EPoSS 2019	ECS BROKERAGE EVENT 2019, BRUSSELS	2 3



THANK YOU!

Contact:

Ο

Wolfgang Gessner EPoSS e.V. Steinplatz 1 10623 Berlin contact@smart-systems-integration.org